Evaluation of ZnO:Ga nanoparticle-based thin-film-transistors

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Zinc oxide, a third-generation semiconductor material with a wide and direct band gap, has received considerable attention due to its excellent optical and electrical properties. The band gap of 3.37eV and a relatively higher exciton binding energy of 60meV [1]. Recently, both n-channel and p-channel back-gate TFTs on Si/SiO₂ substrates were demonstrated by using laboratory synthesized ZnO-nanoparticles (NPs) with a physical spray coating method [2], But the sheet resistance of conductive layer was too high which degraded the performances of TFT. In our previous study, the dramatic improvements of current transportation ability of ZnO-NP based Schottky-gate TFTs by using a unique thermal diffusion type Gadoping process [3] was presented. This study represents the comparison of ZnO MESFET and MISFET properties with a low resistive n-channel layer.

ZnO-NPs were synthesized using an arc-discharge-mediated gas evaporation process with a chamber pressure of 610 Torr and an arc current of 20 A [4]. Diffusion type Ga-doping into ZnO-NPs was carried out according to ref. [5], i.e. mixing ZnO-NPs with Ga₂O₃-NPs and thermally treated in open-air at 800° C for 60 min. Particles were dispersed in ultrapure water by ultrasonic homogenization and centrifugation processes, which can remove residual Ga₂O₃-NPs. Obtained dispersions (median size of 240 nm) were sprayed onto quartz and Si (covered with 100 nm SiO₂) substrates with 5 and 10 s intervals for ~13 and 22 min using a wide-used air-brash (**Fig. 1**) with hotplate temperature 500 and 270° C for MESFET and MISFET fabrication process, respectively. For both FET operations, 0.4 x 0.4 mm² Al electrodes (ohmic source and drain) with a distance of 450 µm were deposited. A 30nm gold electrode was used as a MEStop-gate. **Figs. 2(a)** and **2(b)** show the cross-sectional illustrations of ZnO MISFET and MESFET, respectively.

Previous analyses indicate that the resistance value falls from the order of MΩ/sq to sub-kΩ/sq by thermal treatment with Ga₂O₃ NPs and Ga incorporated into ZnO-NPs with substituting for Zn; i.e. Gadoping was achieved effectively [5]. Fig.3 shows the variations of transconductance (g_m) and ON/OFF current ratio for MES- and MIS-gate-type TFTs. The gate voltage was applied 0 V to -10 V and 0 V to 10 V with 2 V step to measure the I_D - V_D characteristics. The MIS-gate-type TFTs on Si/SiO₂ substrates showed an improved transconductance (g_m=1.9µS) compared with MES-gate-type TFTs on quartz substrates (g_m=0.6µS) . The value of I_{OFF}/I_{ON} ratio @ V_D =10 V was 0.05 in MIS-gate-type, which is one order of magnitude smaller than the value of 0.17 in MES-gate-type. Details should be shown in the presentation. Thus the effect of our unique Ga-doping for ZnO-NPs was clearly observed.

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